

Article

Mechanical Properties of Electrolytically Produced Copper Coatings Reinforced with Pigment Particles

Ivana O. Mladenović ¹, Marija M. Vuksanović ², Stevan P. Dimitrijević ³, Rastko Vasilic ⁴, Vesna J. Radojević ⁵, Dana G. Vasiljević-Radović ¹, and Nebojša D. Nikolić ^{1,*}

¹ University of Belgrade, Institute of Chemistry, Technology and Metallurgy, Njegoševa 12, 11 000 Belgrade, Serbia; ivana.mladenovic@ihtm.bg.ac.rs (I.O.M.); dana@nanosys.ihtm.bg.ac.rs (D.G.V.R.);

² University of Belgrade, VINČA Institute of Nuclear Sciences – National Institute of the Republic of Serbia, Belgrade, Serbia; marija.vuksanovic@vin.bg.ac.rs (M.M.V.);

³ University of Belgrade, Innovation Centre Faculty of Technology and Metallurgy, Karnegijeva 4, 11000 Belgrade, Serbia; sdimitrijevic@tmf.bg.ac.rs (S.P.D.);

⁴ University of Belgrade, Faculty of Physics, Studentski Trg 12-16, 11 000 Belgrade, Serbia; rastko.vasilic@ff.bg.ac.rs (R.V.);

⁵ University of Belgrade, Faculty of Technology and Metallurgy, Karnegijeva 4, 11 000 Belgrade, Serbia; vesnar@tmf.bg.ac.rs (V.J.R.);

* Correspondence: nnikolic@ihtm.bg.ac.rs (N.D.N.); <https://orcid.org/0000-0002-6385-5714>; Tel.: + 381 11 337 03 90

Supplementary

The values of the composite and the calculated coating hardness by application of Chicot–Lesage composite hardness model (C–L CHM) for pure copper and various CuMC–PigP coatings

Table S1. The values of the composite, H_c and the coating hardness, H_{coat} calculated by application of C–L CHM for pure copper ($c = 0$ wt %) and CuMC–PigP coatings with a concentration of the pigment particles of 0.50 and 1.00 wt %. RID – relative indentation depth; P – applied load.

P / N	$c = 0$ wt %			$c = 0.50$ wt %			$c = 1.00$ wt %		
	RID	H_c / GPa	H_{coat} / GPa	RID	H_c / GPa	H_{coat} / GPa	RID	H_c / GPa	H_{coat} / GPa
0.04903	0.121118	0.664156	0.71593	0.090588	0.782356	0.902283	0.068425	0.865619	1.027192
0.09806	0.15528	0.808145	0.78677	0.111933	1.024857	1.064553	0.086782	1.076262	1.143398
0.19612	0.20000	0.974289	0.910716	0.151261	1.122424	1.114832	0.115287	1.219692	1.236984
0.24515	0.224638	0.965367	0.877815	0.162437	1.216601	1.206067	0.126836	1.259614	1.267543
0.39224	0.266046	1.101199	1.014576	0.201681	1.262727	1.239769	0.158211	1.295293	1.289841
0.4903	0.287267	1.180636	1.106959	0.218487	1.344916	1.332017	0.17223	1.366266	1.362313
0.63739	0.322878	1.214939	1.139544	0.243697	1.405365	1.403703	0.186916	1.508002	1.520152
0.88254	0.383023	1.195394	1.09294	0.277983	1.49549	1.52391	0.216956	1.549817	1.578189
0.9806	0.402692	1.201635	1.097312	0.300504	1.421926	1.425183	0.228438	1.553262	1.585819
1.4709	0.485507	1.239988	1.134589	0.369748	1.408827	1.408492	0.284846	1.498479	1.531893
1.9612	0.563147	1.228865	1.101482	0.422689	1.437361	1.453339	0.323097	1.552902	1.615885
2.9418	0.672878	1.291119	1.189684	0.529412	1.374397	1.347113	0.400534	1.515736	1.577841

Table S2. The values of the composite, H_c and the coating hardness, H_{coat} calculated by application of C-L CHM for CuMC–PigP coatings with a concentration of the pigment particles of 1.50 and 3.00 wt %. RID – relative indentation depth; P – applied load.

P / N	$c = 1.50 \text{ wt \%}$			$c = 3.00 \text{ wt \%}$		
	RID	H_c / GPa	H_{coat}/GPa	RID	H_c / GPa	H_{coat}/GPa
0.04903	0.062032	0.952473	1.103057	0.05689	1.122424	1.224458
0.09806	0.08019	1.139896	1.202366	0.075853	1.262727	1.299895
0.19612	0.107937	1.258357	1.275661	0.104425	1.332545	1.342202
0.24515	0.117841	1.319641	1.327267	0.109671	1.510125	1.499015
0.39224	0.146032	1.374916	1.374664	0.136157	1.567619	1.564674
0.4903	0.153968	1.546032	1.550518	0.149368	1.628225	1.632369
0.63739	0.174794	1.559455	1.5728	0.166498	1.703545	1.723908
0.88254	0.200	1.649276	1.687658	0.192794	1.759198	1.810378
0.9806	0.209524	1.669721	1.718673	0.201643	1.78686	1.851994
1.4709	0.260317	1.62254	1.687999	0.246523	1.793221	1.905448
1.9612	0.303937	1.586993	1.659097	0.290771	1.718645	1.842582
2.9418	0.374667	1.566542	1.651889	0.362516	1.658541	1.796041

The cathodic polarization curves for copper electrodeposition from the electrolytes without and with added the pigment particles

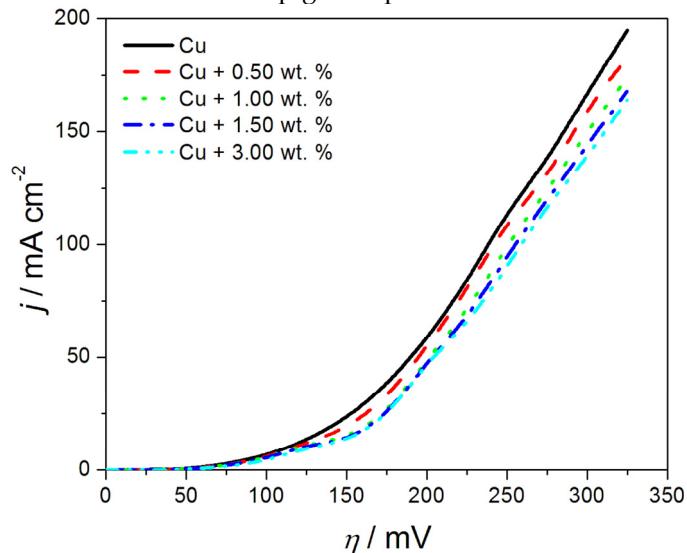


Figure S1. The cathodic polarization curves for Cu electrodeposition recorded from the pigment-free electrolyte, and from electrolytes with an addition of the pigment particles.

The working electrode (cathode): brass; The counter electrode (anode): copper; reference electrode: copper.

The electrolyte stirring: magnetic stirring (100 rpm).

Temperature: the room temperature.